

L Number	Hits	Search Text	DB	Time stamp
-	1997	134/198-200.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/26 14:30
-	241	134/198-200.ccls. and (semiconductor or wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/26 14:54
-	39	(134/198-200.ccls. and (semiconductor or wafer or substrate)) and ((nozzle or spray\$3) with (fan or plane or planar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/26 14:49
-	4133	239/\$.ccls. and ((nozzle or spray\$3) with (fan or plane or planar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/26 16:58
-	316	(239/\$.ccls. and ((nozzle or spray\$3) with (fan or plane or planar))) and (semiconductor or wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/26 14:55
-	12	((239/\$.ccls. and ((nozzle or spray\$3) with (fan or plane or planar))) and (semiconductor or wafer or substrate)) and 134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/26 14:55
-	1034	216/2,92.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/26 16:58
-	51	216/2,92.ccls. and ((nozzle or spray\$3) with (fan or plane or planar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 08:48
-	2720	134/2,34.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 08:48
-	89	134/2,34.ccls. and ((nozzle or spray\$3) with (fan or plane or planar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 08:55
-	285	156/345.21,345.51.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 08:56
-	16	156/345.21,345.51.ccls. and ((nozzle or spray\$3) with (fan or plane or planar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 08:56

-	389	156/345.21,345.51,345.54,345.55.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 08:56
-	17	156/345.21,345.51,345.54,345.55.ccls. and ((nozzle or spray\$3) with (fan or plane or planar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 08:56